



# 100% Material Declaration Data Sheet PCG44

PK116 (v1.3) July 29, 2011

**Average Weight: 2.3596g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die (FPGA)</b>					<b>0.007637</b>	<b>0.32</b>
	Silicon	7440-21-3	100.00	Silicon IC	0.007637	
<b>Die attach material</b>					<b>0.001992</b>	<b>0.08</b>
	Resin	Trade Secret	25.00		0.000498	
	Silver (Ag)	7440-22-4	75.00		0.001494	
<b>Mold Compound</b>					<b>1.825990</b>	<b>77.38</b>
	Resin	Trade Secret	7.50		0.136949	
	Silica	60676-86-0	86.00	Filler	1.570351	
	Carbon Black	1333-86-4	0.50	Polymer	0.009130	
	Epoxy Cresol Novolac	Trade Secret	2.00	Hardener	0.036520	
	Phenolic Resin	Trade Secret	4.00	Colouring	0.073040	
<b>Lead Frame</b>					<b>0.498490</b>	<b>21.13</b>
	Copper (Cu)	7440-50-8	99.90	Base metal	0.497992	
	Zirconium (Zr)	7440-67-7	0.10	Base metal	0.000498	
<b>Lead Frame Plating</b>					<b>0.001490</b>	<b>0.06</b>
	Silver (Ag)	7440-22-4	100.00	Base metal	0.001490	
<b>Gold Wire</b>					<b>0.001818</b>	<b>0.08</b>
	Gold	7440-57-5	100.00	Metallurgy	0.001818	
<b>External Plating</b>					<b>0.022210</b>	<b>0.94</b>
	Tin (Sn)	7440-31-5	100.00	Base metal	0.022210	

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/21/06	1.0	Initial Release
6/08/06	1.1	100% Material Declaration
9/28/06	1.2	Updated component descriptions
7/29/11	1.3	Update resin component weight

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